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June 2014

#### FDMA430NZ

### Single N-Channel 2.5V Specified PowerTrench® MOSFET

**30V**, **5.0A**, **40m** $\Omega$ 

#### **General Description**

This Single N-Channel MOSFET has been designed using Fairchild Semiconductor's advanced Power Trench process to optimize the R<sub>DS</sub>(on) @V<sub>GS</sub>=2.5V on special MicroFET leadframe.

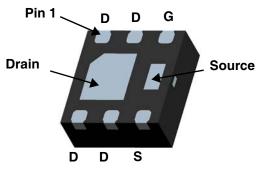
#### **Applications**

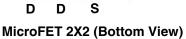
■ Li-Ion Battery Pack

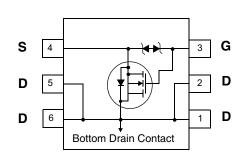


#### **Features**

- $R_{DS(on)} = 40m\Omega$  @  $V_{GS} = 4.5 \text{ V}$ ,  $I_D = 5.0 \text{A}$
- $R_{DS(on)} = 50 \text{m}\Omega$  @  $V_{GS} = 2.5 \text{ V}$ ,  $I_D = 4.5 \text{A}$
- Low Profile-0.8mm maximum-in the new package MicroFET 2x2 mm
- HBM ESD protection level > 2.5kV typical (Note 3)
- Free from halogenated compounds and antimony oxides
- RoHS Compliant







#### Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DSS}$	Drain-Source Voltage	30	V	
$V_{GSS}$	Gate-Source Voltage		±12	V
ı	Drain Current -Continuous	(Note 1a)	5.0	۸
'D	-Pulsed		20	A
В	Power dissipation (Steady State)	(Note 1a)	2.4	w
$P_{D}$		(Note 1b)	0.9	] vv
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	145	· C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Reel Size	Tape Width	Quantity
430	FDMA430NZ	7"	8 mm	3000 units

Max Units

### **Electrical Characteristics** $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Parameter

		ı					
Off Characteristics							
B <sub>VDSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V , I_D = 250 \mu A$	30			V	
$\frac{\Delta B_{VDSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$ , Referenced to 25°C		25.2		mV/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V,$			1	μА	
I <sub>GSS</sub>	Gate-Body Leakage,	$V_{GS} = \pm 12V, \ V_{DS} = 0V$			±10	μΑ	

**Test Conditions** 

#### On Characteristics (Note 2)

Symbol

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.6	0.81	1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C		-3.2		mV/°C
		$V_{GS} = 4.5V, I_D = 5.0A$		23.6	40	
	Static Drain-Source On-Resistance	$V_{GS} = 4.0V, I_D = 5.0A$		23.9	41	mΩ
R <sub>DS(ON)</sub>		$V_{GS} = 3.1V, I_{D} = 4.5A$		25.4	43	
I IDS(ON)		$V_{GS} = 2.5V, I_{D} = 4.5A$		27.6	50	11122
		$V_{GS} = 4.5V, I_D = 5.0A,$ $T_J = 150$ °C		37.0	61	
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5V, I_{D} = 5.0A$		25.6		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	$V_{DS} = 10V, V_{GS} = 0V,$	600	800	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0MHz	110	150	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		75	115	pF
$R_G$	Gate Resistance	f = 1.0MHz	3.5		Ω

#### **Switching Characteristics** (Note 2)

t <sub>d(on)</sub>	Turn-On Delay Time		8.3	17	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 10V, I_{D} = 1A$	7.1	15	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 4.5V$ , $R_{GEN} = 6\Omega$	18.1	37	ns
t <sub>f</sub>	Turn-Off Fall Time		6.0	12	ns
$Q_g$	Total Gate Charge	V 40V L 5.0A	7.3	11	nC
$Q_{gs}$	Gate-Source Charge $V_{DS} = 10V$ , $I_D = 5.0A$ , $V_{GS} = 4.5V$		0.8	2	nC
$Q_{gd}$	Gate-Drain Charge	VGS = 4.3 V	1.9	3	nC

#### **Drain-Source Diode Characteristics and Maximum Ratings**

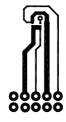
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				2.0	Α
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 2.0A$		0.69	1.2	V
t <sub>rr</sub>	Diode Reverse Recovery Time	I <sub>F</sub> = 5.0A,			17	ns
Q <sub>rr</sub>	Diode Reverse Recovery Charge	di/dt = 100A/μs			5	nC

Notes:

1. R<sub>0JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.



a. 52 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 145 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width <  $300~\mu s$ , Duty Cycle < 2.0%3. The diode connected between the gate and the source serves only as proection against ESD. No gate overvoltage rating is implied.

#### Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

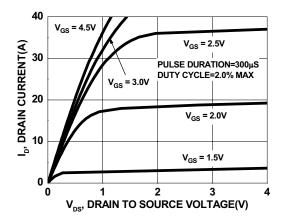


Figure 1. On Region Characteristics

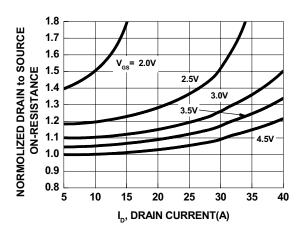


Figure 2. On-Resistance vs Drain Current and Gate Voltage

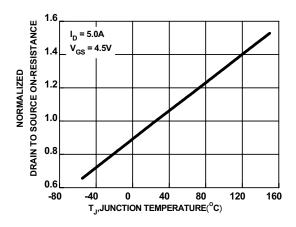


Figure 3. Normalized On Resistance vs Junction Temperature

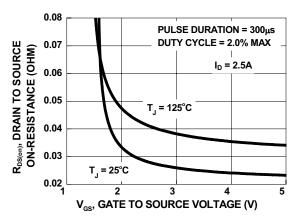


Figure 4. On-Resistance vs Gate to Source Votlage

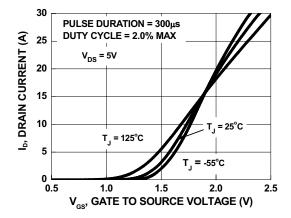


Figure 5. Transfer Characteristics

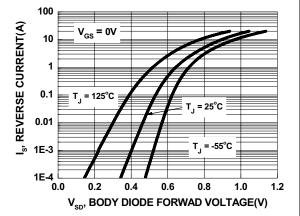
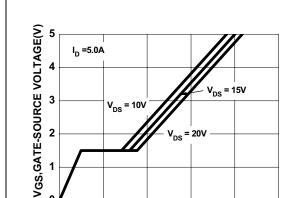
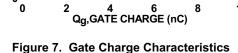


Figure 6. Source to Drain Diode Forward Voltage vs Source Current



Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted



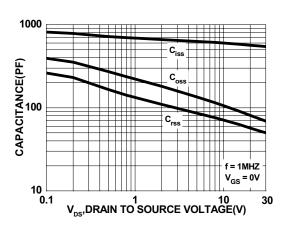


Figure 8. Capacitance vs Drain to Source Voltage

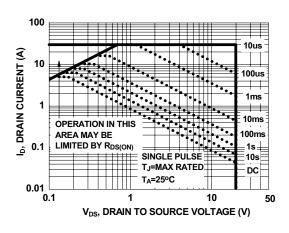


Figure 9. Safe Operating Area

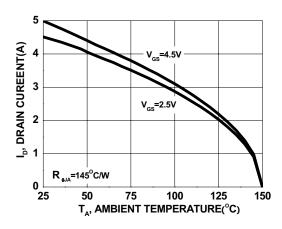
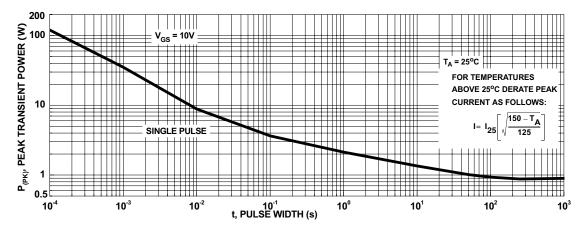


Figure 10. Maximum Continuous Drain Current vs
Ambient Temperature



10

Figure 11. Single Pulse Maximum Power Dissipation

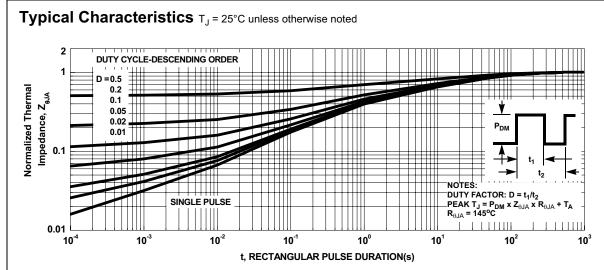
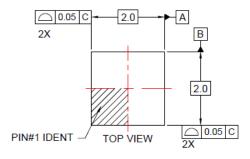
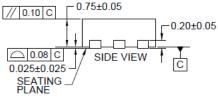
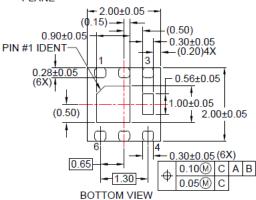


Figure 12. Transient Thermal Response Curve

#### **Dimensional Outline and Pad Layout**

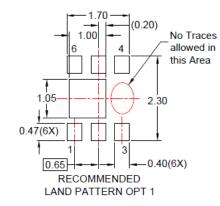


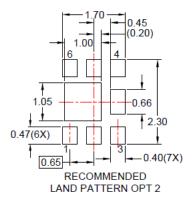




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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP06Lrev4.







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